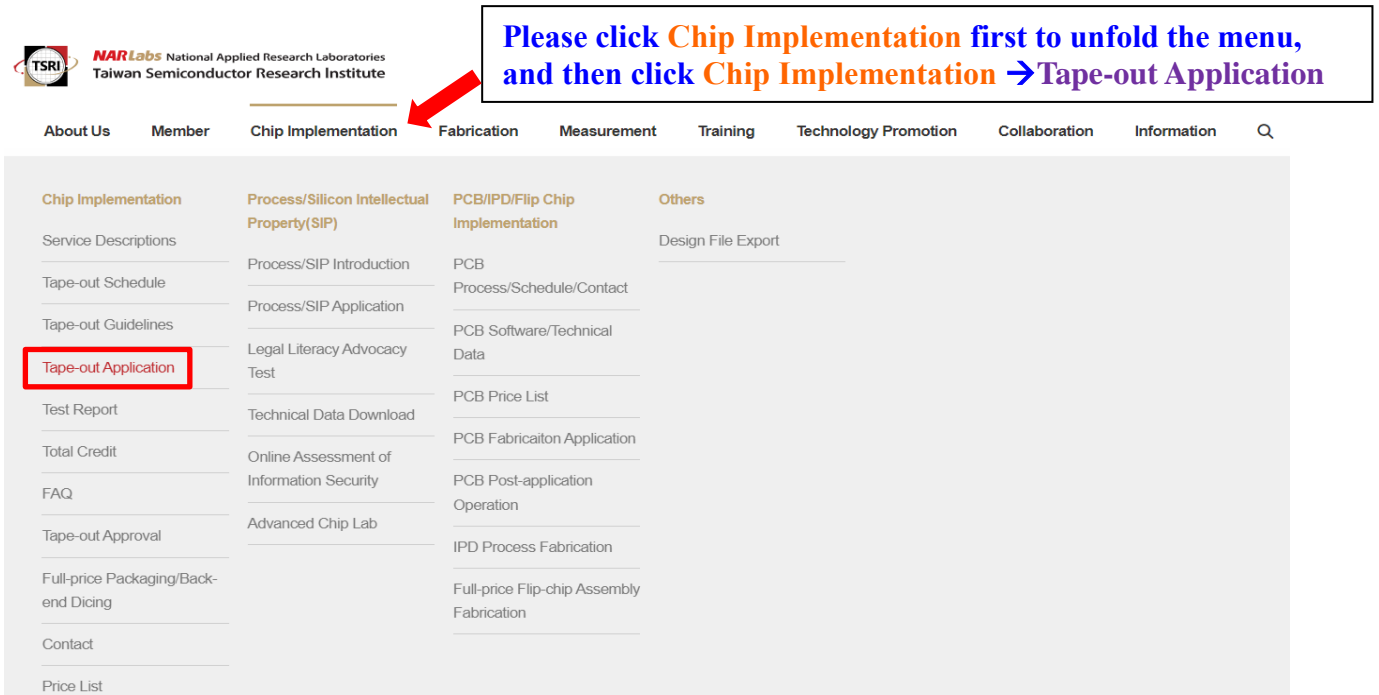


Tape-out Application Website Instructions and Notes

I. How to visit the tape-out application website:

Step 1: Please go to the TSRI's official website and click **Chip Implementation** → **Chip Implementation** → **Tape-out Application**.



The screenshot shows the TSRI website's main navigation menu. The 'Chip Implementation' menu item is highlighted with a red box, and a red arrow points to it from a callout box. The callout box contains the text: 'Please click **Chip Implementation** first to unfold the menu, and then click **Chip Implementation** → **Tape-out Application**'. Below the navigation menu, a grid of service categories is displayed, with 'Tape-out Application' highlighted in a red box under the 'Chip Implementation' category.

TSRI **NAR Labs** National Applied Research Laboratories
Taiwan Semiconductor Research Institute

About Us Member **Chip Implementation** Fabrication Measurement Training Technology Promotion Collaboration Information Q

Chip Implementation Process/Silicon Intellectual Property (SIP) PCB/IPD/Flip Chip Implementation Others

Service Descriptions Process/SIP Introduction PCB Design File Export

Tape-out Schedule Process/SIP Application Process/Schedule/Contact

Tape-out Guidelines Legal Literacy Advocacy Test PCB Software/Technical Data

Tape-out Application Technical Data Download PCB Price List

Test Report Online Assessment of Information Security PCB Fabrication Application

Total Credit Advanced Chip Lab PCB Post-application Operation

FAQ IPD Process Fabrication

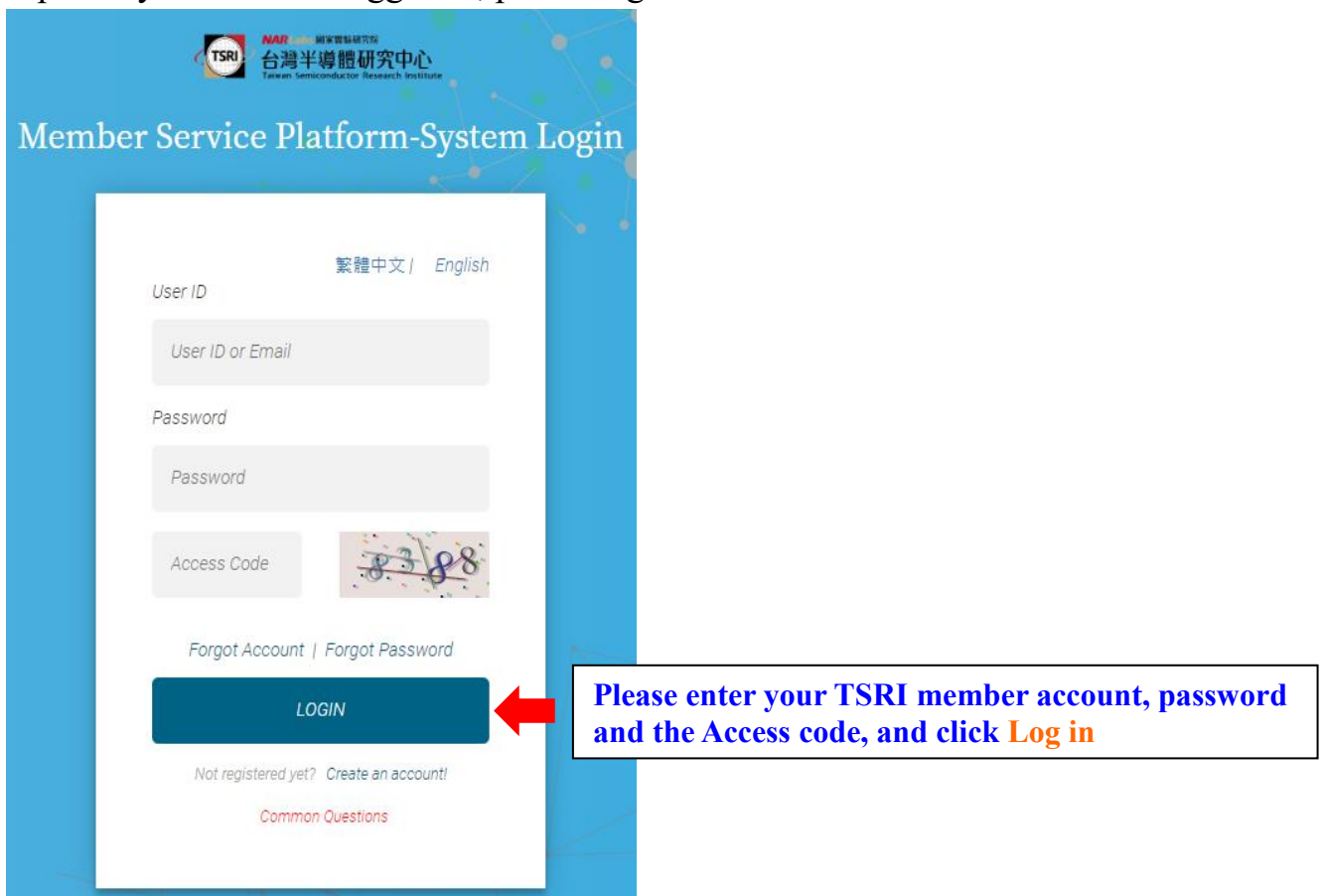
Tape-out Approval Full-price Flip-chip Assembly Fabrication

Full-price Packaging/Back-end Dicing

Contact

Price List

Step 2: If you have not logged in, please log in first.



The screenshot shows the 'Member Service Platform-System Login' page. The page has a blue header with the TSRI logo and the text 'Member Service Platform-System Login'. Below the header, there is a login form with fields for 'User ID or Email', 'Password', and 'Access Code'. A red arrow points to the 'LOGIN' button from a callout box. The callout box contains the text: 'Please enter your TSRI member account, password and the Access code, and click **Log in**'. At the bottom of the form, there are links for 'Forgot Account | Forgot Password', 'Not registered yet? Create an account!', and 'Common Questions'.

TSRI **NAR Labs** 國家實驗研究院
台灣半導體研究中心
Taiwan Semiconductor Research Institute

Member Service Platform-System Login

繁體中文 | English

User ID

User ID or Email

Password

Password

Access Code

Forgot Account | Forgot Password

LOGIN

Not registered yet? Create an account!

Common Questions

Please enter your TSRI member account, password and the Access code, and click **Log in**

Step 3:

The system will navigate you to the homepage of the tape-out application website.



繁體中文

Chip Manufacturing Application System

Welcome to the Chip Manufacturing Application System of NARLabs Taiwan Semiconductor Research Institute. Before you proceed with your application, please carefully read the table and notes below to confirm your eligibility for the selected chip type.

(1) The asterisks in the first three rows of the table (Process Permission, Class Roster, Professor Intellectual Property Rights Affidavit) indicate the steps that must be completed before applying for a process. For example, before applying for the manufacturing of educational chips, your Advisor must obtain process permission, and you must receive authorization from the professor to use the process. The professor must also submit the class roster and the intellectual property rights affidavit to our service contact for database input.

(2) The asterisk in the last row, "Test Report," indicates that, after receiving the chip, you must complete the upload of the chip's test report within a specified timeframe. Except for full-price chips, the other types of chips all require applicants to upload the chip's test report after receiving the chip.

Please refer to the notes for additional information. If you confirm that you meet the eligibility criteria, please click the "Start New Tape-out Application" button at the bottom of this page.

Chip Type	Process Permission	Class Roster	Professor Intellectual Property Rights Affidavit	Test Report	Others
Quick-Review Partial-price Chip	★	--	★	★	
Advanced Partial-price Chip	★	--	★	★	
Educational Chip	★	★	★	★	
New Faculty Discount	★	--	★	★	New Faculty Discount Proof
Superior Chip Discount	★	--	★	★	
Full-price Chip	★	--	--	--	

Notes:

- Process Permission: The applicant's Advisor must have valid process permission (for educational chips, the professor must have valid process permission). Applicants must have professor-approved access to the process.
- Full-price Chip applicants must personally have valid process permission or provide a declaration of legal use of process information for chip manufacturing.
- Class Roster: A class roster is a document that a professor must provide to TSRI in advance. Students listed on the roster can apply for educational chips during the valid application period.
- Test Report:
 - If an applicant has one or more overdue test reports, regardless of chip type, they cannot submit a new application.
 - For advanced chips (including Advanced Partial-price, Quick-review of Partial-price, New faculty discount, and Superior Chip Discount), if the professor and their students collectively have accumulated more than three overdue test reports for this chip type, both the professor and their students are ineligible to submit new applications.
 - For educational chips, if the professor and their students collectively have accumulated more than six overdue test reports for this chip type, both the professor and their students are ineligible to submit new applications.
 - After completing the test report upload, the submission status will be marked as "Uploaded," and you can proceed with a new application.
- New Faculty Discount: Professors must provide proof of the new faculty discount in advance to TSRI for verification and record-keeping so that they and their students can apply for this chip type. Please note that once approved, a limited quantity and volume of chips are available for free of charge and without review for this chip type. If the allocated quantity or volume is exceeded, new applications cannot be submitted.
- Superior Chip Discount: Data for this chip type is organized and documented by TSRI. Professors and students can apply for this chip type once the data is input into the system. Please be aware that this chip type comes with a limited quantity of chips that are both free and exempt from review. If the allocated quantity or volume has been exceeded, new applications cannot be submitted.
- If you have any questions related to the application, please refer to [Tape-out Guidelines](#).

[View Application Summary](#)

[Start New Tape-out Application](#)

[Download Application Manual](#)

Related Link

- New Tape-out Application
- Check Your Tape-out Qualification
- Tape-out Application Summary
- List of Tape-out Schedule
- Tape-out Historical Data
- Application Manual
- Application Flow Chart
- Tape-out Approval
- Payment Inquiry
- Tape-out Guidelines
- Test Report
- Process Application
- Frequently Asked Questions
- Point of Contact
- TSRI Homepage




CONTACT US

Hsinchu : 300091 No.26, Prosperity Road I, Hsinchu Science Park, Hsinchu 300091, Taiwan, R.O.C. TEL 03-5773693 FAX 03-5713403
Tainan : 704017 No.25, Xiaodong Road, Tainan City 704017, Taiwan, R.O.C. TEL 06-2090160 FAX 06-2086069
NCKU Chimei Building : 701401 7F, Chimei Building, Tzu-Chiang Campus, No.1, University Road, Tainan City 701401, Taiwan, R.O.C. TEL 06-2087971 FAX 06-2089122
Best viewed at a resolution of 1366x768 or higher.

II. Step-by-step guide to tape-out application:

Step 0: Please read the descriptions on the tape-out application website to make sure that you are eligible for tape-out ([click the link → Check Your Tape-out Qualification on the right for relevant eligibility descriptions](#)), and then click “New Tape-out Application” to start the application process:

**NAR Labs** National Applied Research Laboratories
Taiwan Semiconductor Research Institute

[繁體中文](#)

Chip Manufacturing Application System

Welcome to the Chip Manufacturing Application System of NAR Labs Taiwan Semiconductor Research Institute. Before you proceed with your application, please carefully read the table and notes below to confirm your eligibility for the selected chip type:

(1) The asterisks in the first three rows of the table (Process Permission, Class Roster, Professor Intellectual Property Rights Affidavit) indicate the steps that must be completed before applying for a process. For example, before applying for the manufacturing of educational chips, your Advisor must obtain process permission, and you must receive authorization from the professor to use the process. The professor must also submit the class roster and the intellectual property rights affidavit to our service contact for database input.

(2) The asterisk in the last row, "Test Report," indicates that, after receiving the chip, you must complete the upload of the chip's test report within a specified timeframe. Except for full-price chips, the other types of chips all require applicants to upload the chip's test report after receiving the chip. Please refer to the notes for additional information. If you confirm that you meet the eligibility criteria, please click the "Start New Tape-out Application" button at the bottom of this page.

Chip Type	Process Permission	Class Roster	Professor Intellectual Property Rights Affidavit	Test Report	Others
Quick-Review Partial-price Chip	★	--	★	★	
Advanced Partial-price Chip	★	--	★	★	
Educational Chip	★	★	★	★	
New Faculty Discount	★	--	★	★	New Faculty Discount Proof
Superior Chip Discount	★	--	★	★	
Full-price Chip	★	--	--	--	

Notes:

- Process Permission: The applicant's Advisor must have valid process permission (for educational chips, the professor must have valid process permission). Applicants must have professor-approved access to the process.
- Full-price Chip applicants must personally have valid process permission or provide a declaration of legal use of process information for chip manufacturing.
- Class Roster: A class roster is a document that a professor must provide to TSRI in advance. Students listed on the roster can apply for educational chips during the valid application period.
- Test Report:
 - If an applicant has one or more overdue test reports, regardless of chip type, they cannot submit a new application.
 - For advanced chips (including Advanced Partial-price, Quick-review of Partial-price, New faculty discount, and Superior Chip Discount), if the professor and their students collectively have accumulated more than three overdue test reports for this chip type, both the professor and their students are ineligible to submit new applications.
 - For educational chips, if the professor and their students collectively have accumulated more than six overdue test reports for this chip type, both the professor and their students are ineligible to submit new applications.
 - After completing the test report upload, the submission status will be marked as "Uploaded," and you can proceed with a new application.
- New Faculty Discount: Professors must provide proof of the new faculty discount in advance to TSRI for verification and record-keeping so that they and their students can apply for this chip type. Please note that once approved, a limited quantity and volume of chips are available for free of charge and without review for this chip type. If the allocated quantity or volume is exceeded, new applications cannot be submitted.
- Superior Chip Discount: Data for this chip type is organized and documented by TSRI. Professors and students can apply for this chip type once the data is input into the system. Please be aware that this chip type comes with a limited quantity of chips that are both free and exempt from review. If the allocated quantity or volume has been exceeded, new applications cannot be submitted.
- If you have any questions related to the application, please refer to [Tape-out Guidelines](#).

[View Application Summary](#)[Start New Tape-out Application](#)[Download Application Manual](#)

Related Link



Please click Start New Tape-out Application

Step 1: New Tape-out Application: Please select the process, MPW run, and type for application:



STEP 1 : New Tape-out Application → STEP 2 → STEP 3 → STEP 4 → STEP 5 → STEP 6

★Please apply online during the 'Application Start Date' and 'Application Deadline' for each MPW Run in the [List of Chip Tape-out Schedule](#).

Please select the MPW Run and chip type for which you wish to apply:

The current open MPW Schedule and Chip Tape-out type:

Integrated Process Selection:

Select the tape-out MPW run and chip type for application and choose if to use an integration process, and then click Next Step

Instructions:

- If there is no Educational Chip available for selection, it means TSRI yet. Please refer to the Item (2) of [Tape-out Guidelines](#) webpage to pre-submit relevant documents (the Class Roster and Excel file) to TSRI via email at: cisd_edu@narlabs.org.tw

If you have any questions regarding the types of discounted chips for your application, consult your Advisor first to determine which

Ⓞ Please note that chip types that you are not eligible for will not be shown as options

STEP 2: Read application guidelines and instructions.



STEP 1 → STEP 2 : View Tape-out Application Guidelines → STEP 3 → STEP 4 → STEP 5 → STEP 6

Taiwan Semiconductor Research Institute(TSRI)
Guidelines and Instructions forsubmitting an application to advanced chip manufacturing
(Including Partial-price, Quick-review of Partial-price, new professor discount,superior chip discount.)
Time of release: Nov 22, 2023

Please view TSRI's Guidelines and Instructions for submitting an application to advanced chip manufacturing. Partial-price, quick review of Partial-price, new professor discount, superior chip discount, and other kinds of chips, collectively referred to as advanced chips, are all included in the guidelines and instructions. Refer to "Item 8 Fee Calculation Details" for details on the fee calculation and amount limit of chip manufacturing, including new professor discount and superior chip discount. In order to avoid fee calculation issues, users are required to select the correct chip type when submitting a request for chip manufacturing. Chip manufacturing related information is published on [the TSRI's Homepage > News Update](#), which is available for viewing.

I. Eligibility for Submission of Chip manufacturing Applications:
Instructors or students under their supervision may submit an application for chip manufacturing if they have obtained the required qualifications for using process technical data from the Technical Standards and Research Institute (TSRI).

II. Application method for process technical data and chip manufacturing:

1. Users are requested to become TSRI members first:
The website for applying for membership is: <http://www.tsri.org.tw/login/login.jsp>

I have read and understood the content described above.

Please carefully read the guidelines and instructions and click OK.

STEP 3: Complete an application form.

STEP 1 → STEP 2 → STEP 3 : Fill in Application Form → STEP 4 → STEP 5 → STEP 6

Related Link

●Applicant Data:

Applicant/Designer : Teacher A	School : National Tsing Hua University	Department : Department/Institute of Electronic Engineering
*Identity : <input type="text" value="Master"/>	Applicant/Designer's Email : p1.cictest@gmail.com	
Telephone : 03-X773693	Cellular Phone : <input type="text"/>	

Advisor :	School :	Department :
Telephone :	Advisor's Email :	

Co-Advisor : <input type="text" value="Please Select"/>				
Name	School	Department	Telephone	Co-Advisor's Email

Co-Designer : <input type="text" value="Please Select"/>				
Name	School	Department	Telephone	Co-Designer's Email

●Chip Data

Process Technology : D35	MPW Schedule : 111X	Application Type : Partial-price
NSTC (National Science and Technology Council) Project No. : <input type="text"/>	Project Duration : <input type="text"/>	Field/Domain : <input type="text"/>
Project Name : <input type="text"/>		
*Research Topic Name (Chinese) : <input type="text"/>		
*Research Topic Name (English) : <input type="text"/>		
*Category of the Designed Circuit : <input type="checkbox"/> Analog <input type="checkbox"/> Digital <input type="checkbox"/> MEMS <input type="checkbox"/> RF		
Chip-Packaging: <input type="text" value="No"/>		
Review Method : <input type="text" value="Attend the review meeting"/>		
Process Special Options : <input type="checkbox"/> Using Cell-Based Design Kit <input type="checkbox"/> Using TSMC I/O Pad <input type="checkbox"/> No need to remove photoresist while using TSRI's post-processing <input type="checkbox"/> Removal of photoresist is required when using TSRI's post-processing(DieSort:8EA) <input type="checkbox"/> Post-processing handled independently		
*Top cell name : <input type="text"/>		
Integrated Process : NONE		

- New Tape-out Application
- Check Your Tape-out Qualification
- Tape-out Application Summary
- List of Tape-out Schedule
- Tape-out Historical Data
- Application Manual
- Application Flow Chart
- Tape-out Approval
- Payment Inquiry
- Tape-out Guidelines
- Test Report
- Process Application
- Frequently Asked Questions
- Point of Contact
- TSRI Homepage

Ⓞ Please note that fields marked with * are required

Fill in a Tape-out Application Form with relevant information and click Confirm

STEP 3: Screen 1 after completing the application form.

Complete Application form message	
This Chip Tape-out Application No. : D35-111X-A0071	
Application form has been completed	
If you want to proceed to the next step, please click the button: STEP 4: Upload Files STEP 4 Upload Files	
Apply for the next one	View the application form Modify the application form Go back to "Application Summary"

©If you are eligible for application, this screen displays to inform you that the form is completed. You may click the **STEP 4: Upload files** button to proceed to the following steps

STEP 3: Screen 2 after completing the application form.

Application Form Modification Completed Message	
Modification completed, but there are some conditions not met. Please confirm as soon as possible.	
*Applicants A, B, C must have professor-approved access to the process of the current year. As the applicant is not included in this year's user list (process authorization list), please inform your professor to update the process authorization list (excel) after leaving this webpage and provide the relevant information to TSRI as soon as possible. If you have any questions regarding the process application, please contact us via email at: xxx@narlabs.org.tw .	
If you want to proceed with the next step: 'files uploading', please click this STEP 4 Upload Files button	
View the application form	Modify the application form Go back to "Application Summary"

©If you are not eligible for application, the reason shows on this screen. Please check your eligibility according to the description as soon as possible. However, you may still click the **STEP 4: Upload files** button to proceed to the following steps

STEP 4: Upload files.

STEP 1 → STEP 2 → STEP 3 → STEP 4:File Upload → STEP 5 → STEP 6

Process Name : WIN 0.15 UM PHEMT
 MPW Schedule and Application Type : 111X - Partial-price
 Chip Type : pHEMT
 Application No. : P15-111X-P0023

Instructions:

Step 4-1: Click the 'Upload File' button to open the upload file window, and upload the required response file.

Step 4-2: If you have completed the required responses as mentioned above, please click on [STEP 5:GDS File Information](#) to confirm that the AutoDRC Results are correct(*For SL process chip tape-out applications, as GDS files do not need to be uploaded, you can skip STEP 5. After completing the file upload, please click on [STEP6:Confirm Submission](#) to complete the application.

Notice:

1.For applicants who use only the GIPD process or have only MEMS structures and cannot perform LVS approval, there is no need to upload LVS approval result files. If multiple DRC verification result files need to be submitted, such as in the case of integrating the GIPD process with the T18 (or TN90GUTM), you need to submit both the T18-DRC (or TN90GUTM-DRC) and GIPD-DRC files. For other processes, depending on the specific process, you may need to upload DRC, Antenna DRC, Wire Bond DRC, and so on. Please use a text editor to copy the text content of several approval result files into a single plain text file before uploading. Ensure that the file has the extension .drc.summary or .rep. If you have any questions regarding file uploads, please refer to the [Example Instructions](#).

2.Full-price Chip should upload the following file types :

- a. GDS File (Graphical Design System File)
- b. Design Content File(**GDS diagram or bonding-wire diagram**)
- c. DRC Results File(**not required for P15, GaN25, WIPD**)
- d. TRF Document(**Only Cell-Based design projects need to be submitted**)

Please upload files as instructed

3.Applicants of the SL process only need to upload the 'Design Content file' and 'TRF Document'.

4.Applicants of the P15, GaN25, WIPD processes only need to upload the GDS file, Design Content file and TRF Document file.

5.If you are conducting chip design within TSRI' s EDA Cloud, please open your browser within the EDA Cloud environment, enter the URL: <http://ecbs.cic.org.tw/ecbs>, complete the login process, select the accurate project, and then upload the GDS file, DRC Result file and LVS Result file.

Step 4-1: Click the 'Upload File' button to open the upload file window, and upload the required response file.

List of Upload files :


File Type	File Format	File Name	Upload Time	File Size(kb)	File has been uploaded	File Upload
GDS file	GDS file(*.gds or *.db)	NONE	NONE	NONE	File has not been uploaded	<input type="button" value="Upload"/>
Design Content	Design Content file formats:(*.doc, *.docx or *.docm)	NONE	NONE	NONE	File has not been uploaded	<input type="button" value="Upload"/>
DRC Result	DRC Result file formats:(*.drc.summary or *.rep)	NONE	NONE	NONE	File has not been uploaded	<input type="button" value="Upload"/>
LVS Result	LVS Result file formats:(*.lvs.report or *.rep)	NONE	NONE	NONE	File has not been uploaded	<input type="button" value="Upload"/>
TRF Document	TRF Document formats:(TRF.doc, TRF.docx, TRF.docm, trfdoc, trfdocx or trfdocm)	NONE	<p>Click STEP 6: Confirm Sending to switch to the submission confirmation screen for information confirmation, and then the application process is completed</p>			

Step 4-2: If you have completed Step4-1, please click on [STEP 5:The GDS file information](#) to confirm that the AutoDRC results are correct, and you have verified that the response files are correct and do not need any further changes, please click on [STEP 6:Confirm Sending](#) to complete the application.

Click this to go back to the application summary table

After uploading files, you may click STEP 5: GDS file information to check the AutoDRC execution result

STEP 4: Click the “Upload files” button, and the file uploading screen appears.

Process Name : WIN 0.15 UMPHEMT MPW Schedule & Application Type : 111X - Partial-price Chip Type : pHEMT Application No. : P15-111X-P0023	
[Notice]	1.Please do not use Chinese characters, spaces, and special characters as part of the file name, as this may result in download failure.
	2.Before uploading files, please ensure that the DRC approval file you are using is the latest version.
	3.Applicants of the SL process only need to upload the 'Design Content file' and 'TRF Document'.
	4.For Full-price Chips,applicants should upload the GDS file and bonding-wire diagram; Only Cell-Based design projects need to be submitted TRF Document.
	5.Applicants of the P15, GaN25, WIPD processes only need to upload the GDS file, Design Content file and TRF Document file.
	6.If your GDS file exceeds 2.0 GB, please use the Safari browser for the upload.
Upload File Type :	
The GDS File has already been uploaded.	NONE 
File Link	<input type="button" value="Select File"/> <input type="button" value="No Files Selected"/> <input type="button" value="Upload"/>

Click Browse to select files to upload as instructed, and then click the Upload button

STEP 4: File uploading screen.

Process Name : TSMC 0.35 UM Mixed-Signal 2P4M Polycide 3.3/5V MPW Schedule & Application Type : 111X - Partial-price Chip Type : CMOS Application No. : D35-111X-A0071	
[Notice]	1.Please do not use Chinese characters, spaces, and special characters as part of the file name, as this may result in download failure.
	2.Before uploading files, please ensure that the DRC approval file you are using is the latest version.
	3.Applicants of the SL process only need to upload the 'Design Content file' and 'TRF Document'.
	4.For Full-price Chips,applicants should upload the GDS file and bonding-wire diagram; Only Cell-Based design projects need to be submitted TRF Document.
	5.Applicants of the P15, GaN25, WIPD processes only need to upload the GDS file, Design Content file and TRF Document file.
	6.If your GDS file exceeds 2.0 GB, please use the Safari browser for the upload.
Upload File Type :	
The TRF Document has already been uploaded.	TRF.docx@2024/04/23 11:04:15
File Link	<input type="button" value="Select File"/> <input type="button" value="TRF.docx"/> <input type="button" value="Upload"/>

Upload Progress:100%

File upload completed !
File Name : TRF.docx
File Size : 11.67(kb)

The upload progress displays on this page 

STEP 4: File upload completion prompt.

The screenshot shows a software interface with a modal dialog box in the center. The dialog box has a green checkmark icon and the text "proceed to STEP 5: Check the File DRC Result :". Below the text is a progress bar and an "OK" button. A red arrow points to the "OK" button. In the background, a table of notices is visible, and a file upload progress bar shows 100% completion. A blue text box with white text is overlaid on the dialog box.

Process Name : TSMC 0.35 UM Mixed-Signal 2P4M Polycide 3.3/5V
MPW Schedule & Application Type : 111X - Partial-price
Chip Type : CMOS
Application No. : D35-111X-A0071

【Notice】	
1.	Please do not use Chinese characters, spaces, and special characters as part of the file name, as this may result in download failure.
2.	Before uploading files, please ensure that the DRC approval file you are using is the latest version.
3.	Applicants of the SL process only need to upload the 'Design Content file' and 'TRF Document'.
4.	For Full-price Chips, applicants should upload the GDS file and bonding-wire diagram; Only Cell-Based design projects need to be submitted TRF Document.
5.	Applicants of the P15, GaN25, WIPD processes only need to upload the GDS file, Design Content file and TRF Document file.
6.	If your GDS file exceeds 2.0 GB, please use the Safari browser for the upload.

Upload File Type :
The GDS File has already been uploaded.
File Link

Upload Progress: 100%

File Name : GDS.gds
File Size : 11.67(kb)

proceed to STEP 5: Check the File DRC Result :

OK

After the upload is completed, you will be prompted to view GDS file information to check the AutoDRC execution result

STEP 4: File upload completion page.

The screenshot shows the same software interface as the previous image, but with the modal dialog box removed. The file upload progress bar now shows 100% completion. A blue text box with white text is overlaid on the page, pointing to a box containing file upload details. A red arrow points from the text box to the details box.

Process Name : TSMC 0.35 UM Mixed-Signal 2P4M Polycide 3.3/5V
MPW Schedule & Application Type : 111X - Partial-price
Chip Type : CMOS
Application No. : D35-111X-A0071

【Notice】	
1.	Please do not use Chinese characters, spaces, and special characters as part of the file name, as this may result in download failure.
2.	Before uploading files, please ensure that the DRC approval file you are using is the latest version.
3.	Applicants of the SL process only need to upload the 'Design Content file' and 'TRF Document'.
4.	For Full-price Chips, applicants should upload the GDS file and bonding-wire diagram; Only Cell-Based design projects need to be submitted TRF Document.
5.	Applicants of the P15, GaN25, WIPD processes only need to upload the GDS file, Design Content file and TRF Document file.
6.	If your GDS file exceeds 2.0 GB, please use the Safari browser for the upload.

Upload File Type :
The GDS File has already been uploaded.
File Link

GDS.gds@2024/04/23 11:37:28

Upload Progress: 100%

File upload complete!
File Name : GDS.gds
File Size : 11.67(kb)

After the upload is completed, you will be informed of the file name and size

☆ **For cell-based chip applications, cell library setting is required. Please follow the instructions on the upload page for step-by-step setting and upload processes.**

STEP 4: Cell-based chip file upload page Part 1:

STEP 1 → STEP 2 → STEP 3 → STEP 4:File Upload → STEP 5 → STEP 6
Process Name : (目前暫不開放申請)TSMC 16 nm CMOS LOGIC FinFET Compact (Shrink) LL ELK Cu 1P13M 0.8/1.8V MPW Schedule and Application Type : 888A - Partial-price Chip Type : CMOS-CellBased Application No. : TN16FFC-888A-A0016
Instructions: Step 4-1: Please set and confirm the related settings of the Cell Library first. Step 4-2: Click the upload file button to open the file upload window and upload the files required for the response. Step 4-3: After checking and confirming that all the above-required response items are correct, then press the ' Complete Upload ' button Step 4-4: If you have completed Step4-1~Step4-3, please press click on the STEP 5:GDS file information to confirm that the AutoDRC Results are correct(*For SL process chip tape-out applications, as GDS files do not need to be uploaded, you can skip STEP 5. After completing the file upload, please click STEP 6:Confirm Sending to complete the application.
Notice: 1.If there are any changes or updates made in the settings of Step 4-1 or the upload in Step 4-2 , please be sure to click the Complete Upload button in Step 4-3 again. 2.For applicants who use only the GIPD process or have only MEMS structures and cannot perform LVS approval, there is no need to upload LVS approval result files. If multiple DRC verification result files need to be submitted, such as in the case of integrating the GIPD process with the T18 (or TN90GUTM), you need to submit both the T18-DRC (or TN90GUTM-DRC) and GIPD-DRC files. For other processes, depending on the specific process, you may need to upload DRC, Antenna DRC, Wire Bond DRC, and so on. Please use a text editor to copy the text content of several approval result files into a single plain text file before uploading. Ensure that the file has the extension .drc.summary or .rep. If you have any questions regarding file uploads, please refer to the Example Instructions . 3.Full-price Chip should upload the following file types : a. GDS File (Graphical Design System File) b. Design Content File(GDS diagram or bonding-wire diagram) c. DRC Results File(not required for P15, GaN25, WIPD) d. TRF Document(Only Cell-Based design projects need to be submitted) 4.Applicants of the SL process only need to upload the 'Design Content file' and 'TRF Document'. 5.Applicants of the P15, GaN25, WIPD processes only need to upload the GDS file, Design Content file and TRF Document file. 6.If you are conducting chip design within TSRI' s EDA Cloud, please open your browser within the EDA Cloud environment, enter the URL: http://ecbs.cic.org.tw/ecbs , complete the login process, select the accurate project, and then upload the GDS file, DRC Result file and LVS Result file."

STEP 4: Cell-based chip file upload page Part 2:

Step 4-1:Setting up the options related to the Cell Library 🗨

Step 4-1-1:Set the Core Cell available for this process: 🗨

Cell Library Still Not Selected		Cell Library Already Selected
^		^
v		v

Step 4-1-2:Set the IO Cell available for this process: 🗨

IO Library Still Not Selected		IO Library Already Selected
^		^
v		v

Step 4-1-3:Set the IP available for this process: 🗨

IP Still Not Selected		IP Already Selected
^		^
v		v

Step 4-1-4:Set the RAM/ROM available for this process:(It is recommended to use the vi editor on UNIX or LINUX workstations to edit and generate the ROM code, otherwise there may be problems during the ROM generation.) 🗨

RAM/ROM Type	Spec File	ROM code(rom only)	Upload	Delete
v	<input type="button" value="Select File"/> <input type="button" value="No Files Selected"/>	<input type="button" value="Select File"/> <input type="button" value="No Files Selected"/>	<input type="button" value="Upload"/>	

STEP 4: Cell-based chip file upload page Part 3:

Step 4-2: Click the 'Upload File' button to open the upload file window, and upload the required response file.

List of Upload files :

File Type	File Format	File Name	Upload Time	File Size(kb)	File has been uploaded	File Upload
GDS file	GDS file(*.gds or *.db)	a.gds	2024/04/15 09:14:16	28973.199	File has been uploaded	
Design Content	Design Content file formats:(*.doc, *.docx or *.docm)	NONE	NONE	NONE	File has not been uploaded	<input type="button" value="Upload"/>
DRC Result	DRC Result file formats:(*.drc.summary or *.rep)	NONE	NONE	NONE	File has not been uploaded	
LVS Result	LVS Result file formats:(*.lvs.report or *.rep)	NONE	NONE	NONE	File has not been uploaded	
TRF Document	TRF Document formats:(TRF.doc, TRF.docx, TRF.docm, trf.doc, trf.docx or	NONE	NONE	NONE	File has not been uploaded	<input type="button" value="Upload"/>

After the upload is completed, be sure to click the **Complete the upload button**

Step 4-3: After checking & confirming that all the above-required response items are correct, then press the 'Complete Upload' button. ----->

Step 4-4: If you have completed Step4-1~Step4-3, please press click on the [STEP 5:The GDS file information](#) to confirm that the AutoDRC Results are correct, and you have verified that the response files are correct and do not need any further changes, please press click on the [STEP 6:Confirm Sending](#) to complete the application).

STEP 5: View GDS file information.

STEP 1 → STEP 2 → STEP 3 → STEP 4 → STEP 5:GDS file Information → STEP 6

Process Name : TSMC 0.35 UM Mixed-Signal 2P4M Polycide 3.3/5V

MPW Schedule & Application Type : 111X,Partial-price

Chip Type : CMOS

Application No. : D35-111X-A0071

GDS File Information:

DRC Execution Status	GDS file has uploaded, automated Design Rule Check (DRC) process will start after preparing.		
Top Cell Name	NONE	Bottom-Left to Top-Right Coordinates	NONE
List of layers	NONE		
DRC Result Download	If you are conducting chip design within TSRI' s EDA Cloud, please open your browser within the EDA Cloud environment, enter the URL: http://ecbs.cic.org.tw/ecbs , complete the login process, select the accurate project, and then click on the 'GDS File Information' button for the project. Download the DRC Results thereafter."	Explanation of The DRC Violation For Each Process	
Prompt Information	NONE		

Notice:


- 1.After uploading the GDS file, you can go to the '[DRC and Queue Execution Status Inquiry](#)' webpage to check the status of the DRC execution.
- 2.Instructions for P15, GaN25, and WIPD processes are as follows: due to the absence of Calibre DRC in P15, GaN25, and WIPD Processes, there is no online DRC check, and the downloaded DRC Result will be empty.
- 3.If you have already verified that your application data and GDS file are correct and have not yet clicked 'Confirm Sending', please click **STEP 6: Confirm Sending** to complete the application.
- If the status of the project is no longer in the application process, there is no need to click 'STEP 6: Confirm Sending'.
- 4.If the DRC execution status indicates an error in analyzing the GDS file, please send an email to tsri-cbs@narlabs.org.tw to notify the system administrator for assistance.
- 5.You can click the 'Refresh' button at the bottom of this page to obtain real-time information on the DRC file inspection results.

[Refresh](#) [Previous Page](#)

You may click [Refresh](#) at the bottom of this page to obtain the most updated DRC execution status for this application. If the information is correct, you may click the [Step 6: Confirm Sending](#) link to proceed to the next step or go back to the application summary table for revision

Step 6: Confirm Sending.

STEP 1 → STEP 2 → STEP 3 → STEP 4 → STEP 5 → STEP 6: Confirm Sending



NARLabs Taiwan Semiconductor Research Institute Chip Manufacturing Application Table					
					Apply Date: 2024/04/23
Applicant Data					
Identity: Master					
Advisor:	Advisor's School:		Advisor's Department:		
Advisor's Telephone:	Advisor's Email:				
Applicant/Designer: Applicant A	School: National Tsing Hua University		Department: Department/Institute of Electronic Engineering		
Telephone: 03-X773693	Applicant/Designer's Email: p1.cictest@gmail.com				
Chip Data					
Process Name: D35	MPW Schedule: 111X		Application Type: Partial-price		
Research Topic Name (Chinese): TTTT					
Research Topic Name (English): Test					
Category of the Designed Circuit: Analog			Review Method: Attend the review meeting		
Application No.: D35-111X-A0071					
Chip-Packaging: N	Packaging Type:		Packaging Unit:		
Top cell name: Test					
Project Data					
Project No.:	Project Duration:		Field/Domain:		
Project/Plan Name:					
Process Special Options					
List of Upload files :					
File Type	Format Explanations	File Name	Uploading Time	File Size(kb)	File has already been uploaded?
GDS file	GDS file formats: (*.gds or *.db)	GDS.gds	2024/04/23 11:37:28	11.67	Files have been uploaded.
Design Content	Design Content file formats: (*.doc, *.docx or *.docm)	NONE	NONE	NONE	Files have not been uploaded.
DRC Result	DRC Result file formats: (*.drc.summary)	NONE	NONE	NONE	Files have not been uploaded.
LVS Result	LVS Result file formats: (*.lvs.report)	NONE	NONE	NONE	Files have not been uploaded.
TRF Document	TRF Document formats: (TRF.doc, TRF.docx, TRF.docm, trf.doc, trf.docx or trf.docm)	TRF.docx	2024/04/23 11:04:15	11.67	Files have been uploaded.
Confirm Sending					
If you confirm that the application form and uploaded files are correct, please click the 'Confirm Sending' button. If you have not confirmed or need to make further changes to the application form and uploaded files, please go back to the application summary, proceed with the modifications.					
<input type="button" value="Confirm Sending"/> <input type="button" value="Go back to 'Application Summary'"/>					

If you have ensured that the application form content, files uploaded, and GDS file information are correct, you may click the **Confirm Sending button at the bottom of this page to complete the submission of this application!**

Step 6: Confirm Sending - Confirmation prompt after clicking the “Confirm” button.

List of Upload files :

File Type	Format Explanations				
GDS file	GDS file formats:(*.gds or *.db)	GDS.gds			File has already been uploaded.
Design Content	Design Content file formats:(*.doc, *.docx or *.docm)	NONE			Files have not been uploaded.
DRC Result	DRC Result file formats: (*.drc.summary)	NONE	NONE	NONE	Files have not been uploaded.
LVS Result	LVS Result file formats: (*.lvs.report)	NONE	NONE	NONE	Files have not been uploaded.
TRF Document	TRF Document formats:(TRF.doc, TRF.docx, TRF.docm, trf.doc, trf.docx or trf.docm)	TRF.docx	2024/04/23 11:04:15	11.67	Files have been uploaded.

Confirm Sending

If you confirm that the application form and uploaded files are correct, please click the 'Confirm Sending' button. If you have not confirmed or need to make further changes to the application form and uploaded files, please go back to the application summary, proceed with the modifications.

[Confirm Sending](#) | [Go back to "Application Summary"](#)

Are you sure that you want to submit?

[Confirm](#) [Cancel](#)

STEP 6: Confirm Sending - The system confirms with you again after you click “Confirm” on the “Confirm Sending” prompt.

Kind Reminder: Once you click the “Confirm Sending” button, it is impossible to modify the Application Form and upload files any more.

[Confirm](#) [Cancel](#)

STEP 6: Confirm Sending - After clicking the “Sending” button, this screen displays if you are not eligible for application.



©Please check your eligibility or upload missing required files according to the

There are conditions that have not been fulfilled :

The following files have not been uploaded :
Design Content File



STEP 6: Confirm Sending - Success message



Congratulations! You have completed the Application.



If all criteria are met, the system displays this message: Congratulations, you have successfully completed the online application process!

Application Summary Table:

In the application process, you may go to the **Application Summary** (via the “**View Application Summary**” button on the bottom left of the system homepage or the “**Tape-out Application Summary**” link in **Related Link** on the right) at any time to check information on your applications. You can view or modify your application forms, upload files, view GDS file information, create and upload responses to review comments, etc.

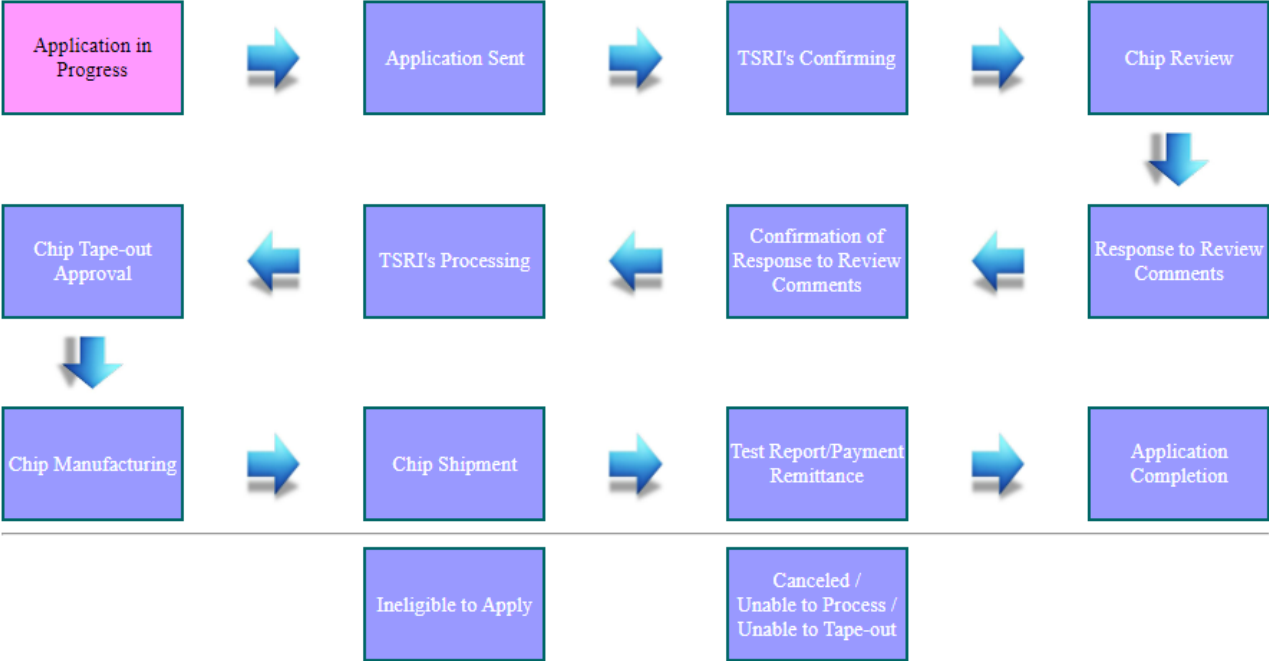
Application Summary												Related Link
Identity	Application Type	Application No.	Application Form	File Upload	GDS Info	Confirm Sending	Review Results	Upload Response to Review Comments	TSRI Processing Info	Application Status	Cancel	
1	Applicant	Partial-price	D35-111X-A0071	Modify View	Upload	View	Submit			Application in Progress		<ul style="list-style-type: none"> ● New Tape-out Application ● Check Your Tape-out Qualification ● Tape-out Application Summary ● List of Tape-out Schedule ● Tape-out Historical Data ● Application Manual ● Application Flow Chart ● Tape-out Approval ● Payment Inquiry ● Tape-out Guidelines ● Test Report ● Process Application ● Frequently Asked Questions ● Point of Contact ● TSRI Homepage
2	Advisor	Partial-price	TN16FFC-888A-A0017	View	View	View	Submit			Application Ineligible	Cancel	
3	Applicant	Partial-price	TN16FFC-888A-A0016	Modify View	Upload	View	Submit			Application in Progress	Cancel	
4	Applicant	Full-price Chip	P15-111X-S0009	View	View	View		N/A	N/A	View	Chip Tape-out Approval	Cancel
5	Applicant	Full-price Chip	U18-111X-S0004	View	View	View		N/A	N/A	View	TSRI's Confirming	Cancel
6	Advisor	Practical-course Chip	D35-112X-T0024	View	View	View	Submit			Application in Progress	Cancel	
7	Advisor	Quick-review Partial-price Chip	D35-112X-R0003	View	View	View	Submit			Application Sent		
8	Applicant	Quick-review Partial-price Chip	D35-112X-R0002	View	View	View	Submit			Application Sent		
9	Applicant	Full-price Chip	P15-111X-S0008	View	View	View		N/A	N/A	View	TSRI's Confirming	Cancel
10	Applicant	Partial-price	D35-111X-A0070	Modify View	Upload	View	Submit			Application in Progress		

1st Page 1 Next Page Last Page Show 10 items per page total 237 data

By clicking the processing progress in the tape-out application summary table, the current **processing step** for the application concerned displays as shown in the following image, helping you understand the current status of your application.

Status of Progress

Partial-price Chip/New Faculty Discount Status of Progress



Related Link:

All links related to tape-out application are listed in the Related Link section on the right. You may click on these links based on your needs. For example, if you need to upload a test report, please click Test Report; if you need to check tape-out guidelines, please click Tape-out Guidelines, and so on.

Related Link

- New Tape-out Application
- Check Your Tape-out Qualification
- Tape-out Application Summary
- List of Tape-out Schedule
- Tape-out Historical Data
- Application Manual
- Application Flow Chart
- Tape-out Approval
- Payment Inquiry
- Tape-out Guidelines
- Test Report
- Process Application
- Frequently Asked Questions
- Point of Contact
- TSRI Homepage

- ☆ For any questions about the use of this system, you may click **Relevant Links**
- “Point of Contact”** for the contact information of persons in charge or use the “Customer Consulting System.” The person in charge will contact you as soon as possible. The TSRI is sincerely at your service!